CARD SOCKETS

Operation:垫高卧式(垫高 1.8mm)D+S 结构 & 3.1Type-C 连接器(24PIN)

Halogen Free | LEAD FREE | RoHS Compliant

ITEM NO.:MC-313H-18 (Consumer Electronics)

(L11.1×W9.84×H 5.2mm & TYPE-C CONNECTORS)

3.1 Type-C CONNECTORS

外焊贴片式 SMT

侧向導入 LATERAL

精密部品 NICETY

可靠 STABILIZE

環保材质 RoHS

Technical parameter

PROJECT \ LEVEL		A[better product]	B[average product]
Electrical Properties	Contact Rating	5A, 24V DC	
	Initial Contact Resistance	30mΩ max.	50mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Skey/PD：100MΩ min.300V DC
	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut
Durable Performance	There No Load	6,500 Cycles	5,500 Cycles
	Rated Load	5,500 Cycles	4,500 Cycles
Storage Temp		25℃/50℃RH (Operating temperature: -35℃～+75℃)	

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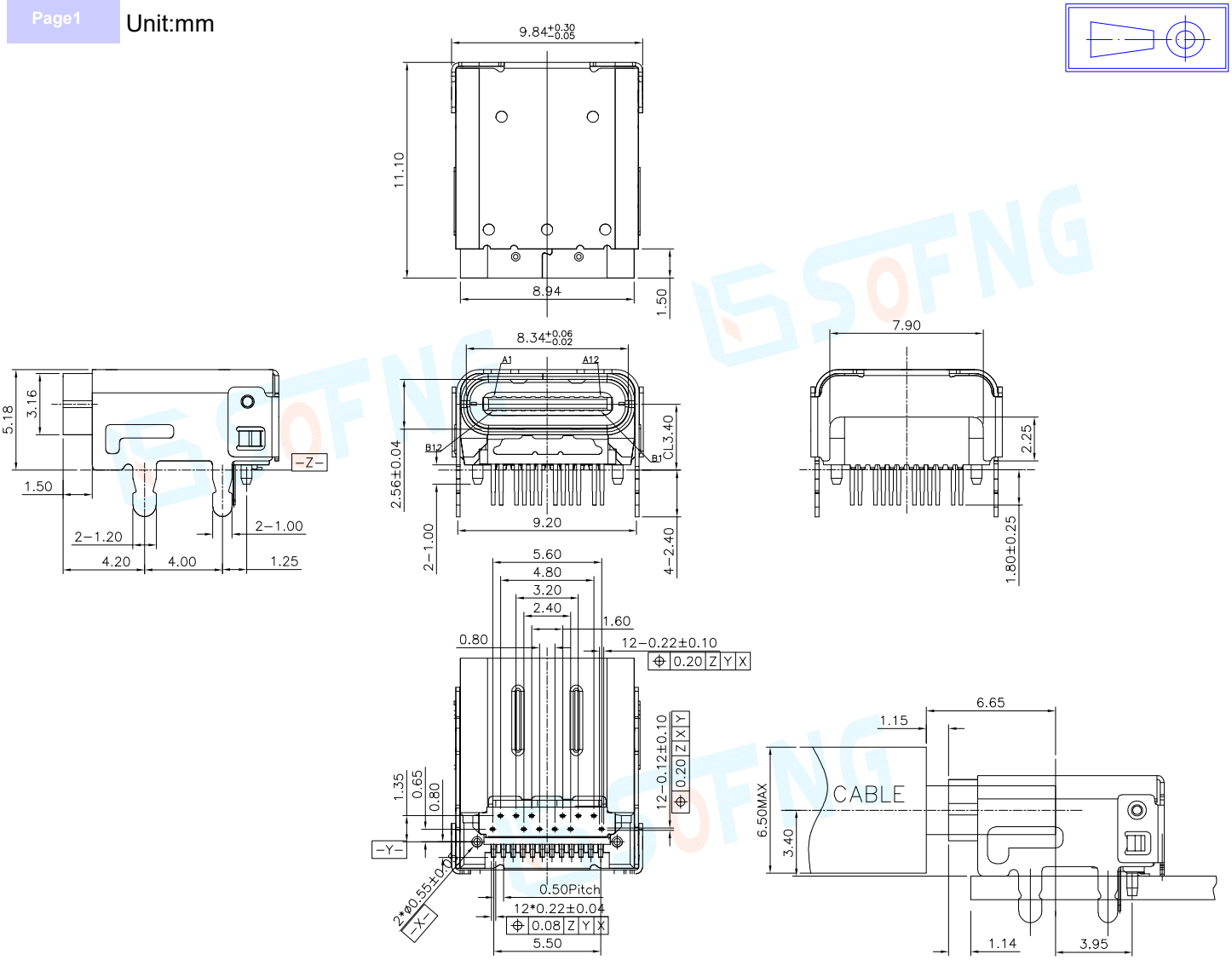
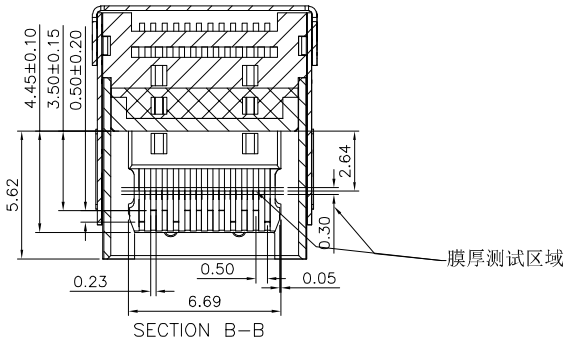
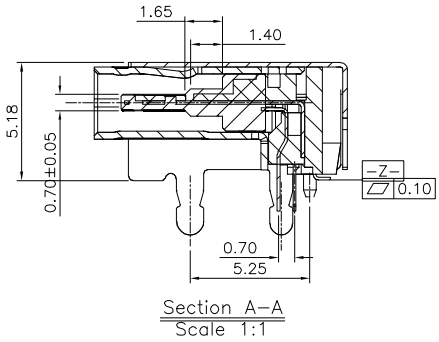
Unit:mm







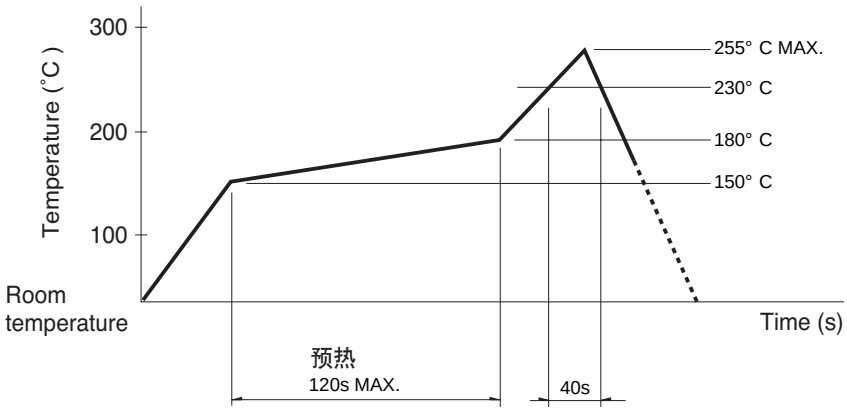
SPECIFED TOLERANCES

UNLESS OTHERWISE

DECIMALS	ANGLES
X.X :±0.25	X.X :±3°
X.XX :±0.15	X.XX :±2°
X.XXX :±0.10	

回流方式的参考举例

1. 加热方式远红外线加热的上下加热方式。
2. 温度测量方式用 V0.1 ～ V0.2 的 CA(K) 或 CC(T) 进行测量。
3. 温度分布



手焊接时

项 目	条 件
焊接温度	350℃max.
连续焊接时间	3s max.
焊剂斗容量	60W max.

自动浸焊时

项 目	条 件
助焊剂附着量	不附着于零部件贴装面的程度
预热温度	印刷电路板焊接面的周围温度 100℃ max.
预热温度时间	60s max.
焊接温度	260℃ max.
焊接浸渍时间	5s max.
焊接次数	2次以下

Material declaration

No.	NAME	MATERIAL	DESCRIPTION
① A	TERMINAL 接触端子	COPPER ALLOY 【G/F】	2.0 μm Ni PLATED OVERALL; 0.25 μm Au PLATED CONTACT AREA; GOLD FLASH ON SOLDER AREA.
② B	HOUSING 基座	THERMOPLASTIC	UL 94V-0,COLOR:BLACK;
③ C	SHIELDING PLATE 屏蔽壳	STAINLESS STEE	【G/F】0.25 μm Ni PLATED OVERALL;
④ D	SHELL 外壳	STAINLESS STEE	【G/F】0.25 μm Ni PLATED OVERALL;
⑤ E	GND RING 接地件	STAINLESS STEE	STAINLESS STEEL;

PRODUCT MEET THE REQUEST OF THE ROHS

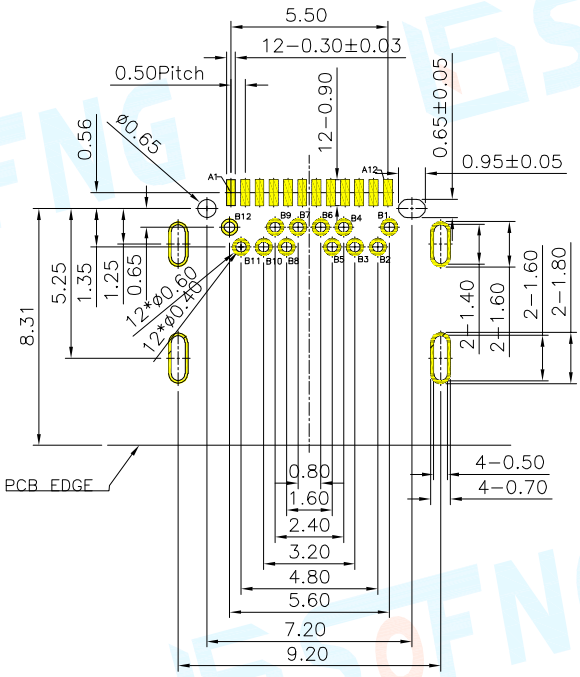
MATTER	RoHs (PPM)
Cd	≤ 100
Pb	≤ 1000
Hg	≤ 1000
Cr6+	≤ 1000
PBB	≤ 1000
PBDE	≤ 1000

MATERIAL

CIRCUIT BOARD SIZE

(Vertical view)

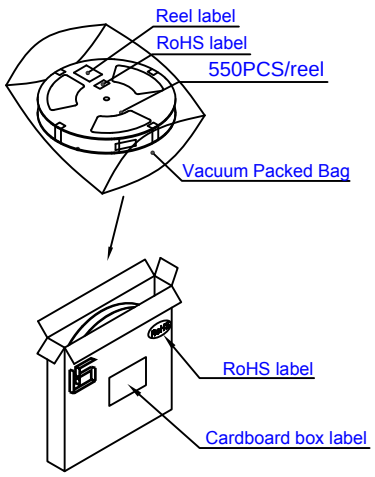
Operating Force	Inward	8.0～20.0N. (1N.=100gram-force)	**Solder-ability (Max.)**	
	Exiting	8.0～20.0N. (1N.=100gram-force)	IR Reflow:255℃,5sec.	Manual:350℃,3sec.



推荐锡膏厚度	0.12mm

PIN ASSIGNMENTS

PIN	Signal NAME	Description	PIN	Signal NAME	Description
A1	GND	Ground return	B12	GND	Ground return
A2	SSTXp1	Positive half of firs SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A3	SSTXn1	Negatice half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A4	V BUS	Bus Power	B9	V BUS	Bus Power
A5	CC1	Configuration Channel	B8	SBU2	Sideband Use(SBU)
A6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A8	SBU1	Sideband Use(SBU)	B5	CC2	Configuration Channel
A9	V BUS	Bus Power	B4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B3	SSTXn2	Negatice half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B2	SSTXp2	Positive half of firs SuperSpeed TX differential pair2
A12	GND	Ground return	B1	GND	Ground return



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